Overview

HP 340S G7 Notebook PC



- 1. Internal Microphones (2)
- 2. Webcam LED
- 3. Webcam Camera
- 4. Touch Pad

- Left
- 5. Power Light
- 6. Drive Light
- 7. SD Card Reader
- 8. Power Button



Overview



- 1. Power
- 2. HDMI Port (Cable not included)
- 3. USB 3.1 Type-A Gen 1
- 4. USB 3.1 Type-A Gen 1

- 5. USB Type-C[™] with Data Only
- 6. Audio Comb Jack
- 7. Optional touch Fingerprint Sensor



Overview

At a Glance

- Preinstalled Windows 10¹, FreeDOS
- Choice of 10th generation Intel[®] Core[™] i7, i5, i3 processors
- Intel[®] Iris[®] Plus graphics for captivating visual and video experiences
- Optional backlit keyboard
- Forget about user names and passwords. Simply log on to Windows and web sites, via using an optional fingerprint sensor²
- Less than 18 mm
- Super-light: 1.47 Kg (3.24 lbs)
- Long battery life gets you through a day of meetings without plugging in. Quickly recharge your PC with HP Fast Charge You'll get up to 50% battery life in just 45 minutes of charging.⁵
- Get a fast and reliable connection in dense wireless environments with gigabit speed Wi-Fi 6^{2, 3, 4}
- Up to 512 GB Solid State Drives
- Up to 16 GB total system memory
- 6.5mm micro-edge display w/ 79.1% screen-to-body ratio

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Sold separately or as an optional feature.

3. Wi-Fi[®] supporting gigabit speeds is achievable with Wi-Fi 6 (802.11ax) when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.

4. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

5. Recharges your battery up to 50% within 45 minutes when the system is off or in standby mode. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP 340S G7 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64¹ Windows 10 Pro 64 (National Academic only)² Windows 10 Home 64¹ Windows 10 Home Single Language 64¹ FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel[®] Core[™] i7-1065G7 processor with Intel[®] Iris[®] Plus Graphics (1.3 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 8 MB cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-1035G1 processor with Intel[®] UHD Graphics (1 GHz base frequency, up to 3.6 GHz with Intel[®] Turbo Boost Technology, 6 MB cache, 4 cores) ^{3,4,5,6}

Intel[®] Core[™] i3-1005G1 processor with Intel[®] UHD Graphics (1.2 GHz base frequency, up to 3.4 GHz with Intel[®] Turbo Boost Technology, 4 MB cache, 2 cores) ^{3,4,5,6}

Processors Family

10th Generation Intel[®] Core[™] i7 processor (i7-1065G7)⁶ 10th Generation Intel[®] Core[™] i5 processor (i5-1035G1)⁶ 10th Generation Intel[®] Core[™] i3 processor (i3-1005G1)⁶

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



CHIPSET

Integrated with processor

GRAPHICS

Integrated

Intel[®] Iris[®] Plus Graphics Intel[®] UHD Graphics (i3-1005G1/i5-1035G1), Intel Iris Plus Graphics (i7-1065G7)⁷

Supports Support HD decode, DX12, HDMI 1.4b

7. HD content required to view HD images.

DISPLAYS

Internal

Non-Touch

35.56 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)^{8,9} 35.56 cm (14") diagonal HD SVA anti-glare WLED-backlit slim, 220 nits, 45% NTSC (1366 x 768)^{8,9}

Display Size

35.56 cm (14")

8. HD content required to view HD images.

9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary M.2 Storage

128 GB M.2 SATA-3 TLC SSD¹⁰ 256 GB PCIe[®] NVMe[™] M.2 SSD¹⁰ 256 GB PCIe[®] 3x2x2 NVMe[™] M.2 + SSD 16 GB 3D Xpoint ¹⁰ 512 GB PCIe[®] NVMe[™] M.2 SSD¹⁰ 512 GB PCIe[®] 3x2x2 NVMe[™] M.2 + SSD 32 GB 3D Xpoint¹⁰

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory 16 GB DDR4-2666 SDRAM¹¹

Memory 12 GB DDR4-2666 SDRAM (1 X 8 GB + 1 X 4 GB)¹¹ 16 GB DDR4-2666 SDRAM (2 X 8 GB)¹¹



Technical Specifications

8 GB DDR4-2666 SDRAM (1 x 8 GB)¹¹ 8 GB DDR4-2666 SDRAM (2 x 4 GB)¹¹ 4 GB DDR4-2666 SDRAM (1 x 4 GB)¹¹

Memory Slots

2 SODIMM DDR4 PC4 SODIMMS, system runs at 2666 Supports Dual Channel Memory

11. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel[®] Dual Band Wireless-AC AX201 Wi-Fi[®] and Bluetooth[®] 5 Combo, non-vPro^{™12} Realtek 802.11ac (2x2) and Bluetooth[®] 5 Combo (MU-MIMO supported)^{*}

Miracast

Native Miracast Support¹³

12. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

13. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

* Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers Integrated dual array Digital Microphones

Camera 720p HD Camera⁸

8. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard Full-size island-style, backlit keyboard¹⁴

Pointing Device Clickpad with multi-touch gesture support



Not all configuration components are available in all regions/countries. c06452802 — DA16554 - Worldwide — Version 3 — October 30, 2019

Function Keys

- ESC: Blank
- F1 system information
- F2 Brightness Down
- F3 Brightness Up
- F4 Display Switching
- F5 Backlight Toggle (for backlit keyboard) or Blank
- F6 Speaker Mute
- F7 Volume Down
- F8 Volume Up
- F9 Rewind
- F10 Start/Stop
- F11 Fast-forward
- F12 Flight Mode

14. Backlit keyboard is an optional feature.

SOFTWARE AND SECURITY

Software

HP Support Assistant¹⁵ Buy Office (Sold separately)

Security Management TPM 2.0 Fingerprint Sensor¹⁶

HP Support Assistant requires Windows and Internet access.
 Fingerprint Sensor is an optional feature

POWER

HP Smart 65 W EM External AC power adapter^{17,18} HP Smart 65 W External AC power adapter^{17,18} HP Smart 45 W External AC power adapter¹⁷

Primary Battery HP Long Life 3-cell, 41 Wh Li-ion¹⁹

Power Cord 1M length power Cord

Battery life Up to 12 hours²⁰

Battery Weight 0.43 lb 0.195 kg

17. Availability may vary by country.

18. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
 19. Battery is internal and not replaceable by customer. Serviceable by warranty.



20. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight Starting at 3.24 lb²¹ Starting at 1.47 kg²¹ Does not include power adapter.

Product Dimensions (w x d x h) 12.76 x 8.86 x 0.7 in 32.4 x 22.5 x 1.79 cm

21. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB 3.1 Type-C[™] Gen 1 2 USB 3.1 Type-A Gen 1 1 HDMI 1.4²² 1 AC power 1 Headphone/microphone combo jack

Expansion Slots

1 multi-format digital media reader Supports SD, SDHC, SDXC

22. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software support depending on country. Batteries have a default one year limited warranty. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. Onsite service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.²³

23. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



COMPATIBILITY

HP USB Essential Keyboard and Mouse	H6L29AA
HP USB-C to HDMI 2.0 Adapter	1WC36AA
HDMI to VGA Adapter	H4F02AA
HP Essential Top Load Case	H2W17AA

CERTIFICATION AND COMPLIANCE

ENERGY STAR[®] certified EPEAT[®] 2019 Silver²⁴

24. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: •IT ECO declaration •US ENERGY STAR [®] •EPEAT [®] 2019 Silver in U.S. Based on US EPEAT [®] registration according to IEEE 1680.1-2018 EPEAT [®] . EPEAT [®] status varies by country. Visit http://www.epeat.net for more information.		
System Configuration	The configuration used for the Energy Notebook model is based on a "Ty		ise Emissions data for the
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	4.14 W	4.164 W	4.056 W
Normal Operation (Long idle)	2.112 W	2.184 W	2.076 W
Sleep	0.372 W	0.384 W	0.372 W
Off	0.192 W	0.228 W	0.192 W
	Energy efficiency data listed is for an ENERGY STAR [®] compliant product if offered within the model family. HP computers marked with the ENERGY STAR [®] Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR [®] specifications for computers. If a model family does not offer ENERGY STAR [®] compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows [®] operating system.		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	14 BTU/hr	14 BTU/hr	14 BTU/hr
Normal Operation (Long idle)	7 BTU/hr	7 BTU/hr	7 BTU/hr
Sleep	1 BTU/hr	1 BTU/hr	1 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr



Technical Specifications

	Heat dissipa for one hou	tion is calculated based on the me	asured watts, assuming	g the service level is attained
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle		2.5		25
Fixed Disk – Random writes		2.5		25
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries		(s) in this product comply with EU	Directive 2006/66/EC	
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: Not Applicable Battery type: Not Applicable			
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <silver> level, see http://www.epeat.net</silver> Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. This product is 96.2% recycle-able when properly disposed of at end of life. 			
Packaging Materials	External:	PAPER/Paper		51 g
		PAPER/Corrugated		230 g
	Internal:	PLASTIC/Polyethylene Expande	ed - EPE	31 g
		PLASTIC/Polyethylene low den	sity - LDPE	9 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos			



Technical Specifications

	Certain Azo Colorants
	• Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
	• Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	• Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	• Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	• Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	• Design packaging materials for ease of disassembly.
	 Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
UD Inc. Councilate	customers who integrate and re-sell HP equipment.
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
HP Inc. Corporate Environmental Information	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html



Technical Specifications

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
_Certificate.pdf
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	
Nominal Operating Voltage	19.5 V
Average Operating Power	4.82W
Integrated graphics	Intel® Iris® Plus Graphics (ICL-i7) Intel® UHD graphics (ICL-i5/i3)
Discrete Graphics	N/A (Switchable graphics design)
Max Operating Power	UMA < 45W
Temperature	
Operating	41° to 95° F (5° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%
Non-operating	5% to 95%
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	1.043 grms
Non-operating	3.5 grms
Altitude (unpressurized)	
Operating	-50 to 10,000 ft (-15 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15 to 12,192 m)
Planned Industry Standard Certifications	
UL	Yes
FCC Compliance	Yes
EPEAT [®]	EPEAT [®] 2019 Silver in U.S. ²⁵
ICES	Yes
ССС	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
EAC	Yes
UKRSERTCOMPUTER	Yes

25. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.



Technical Specifications

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14.0 inch diagonal HD	Outline Dimensions (W x H x D)	316.2 x 198 (mm) max (with PCB Board)
SVALED-backlight; 220 cd/m2; 45% sRGB (1366 x 768)	Active Area	309.4 x 173.95 (mm)
	Weight	280 g max.
	Diagonal Size	14.0 (inch)
	Thickness	3.0 (mm) max
	Interface	eDP 1.2
	Surface Treatment	Anti-glare (AG)
	Touch Enabled	None
	Contrast Ratio	500:1 (typical)
	Refresh Rate	60Hz
	Brightness	220 nit typical
	Pixel Resolution	1366 x 768 (HD)
	Backlight	RGB
	Format of LCD Pixel Arrangement	LED
	Color Gamut Coverage	45%
	Color Depth	6 bits
	Viewing Angle	45/45/20/45
		-21/20/20/20
14.0 inch Diagonal FHD	Outline Dimensions (W x H x D)	316.17 x 198.04 (mm) max (with PCB Board)
Anti-Glare WLED UWVA	Outline Dimensions (W x H x D) Active Area	316.17 x 198.04 (mm) max (with PCB Board) 309.37 X 174.02 (mm)
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	·····	
Anti-Glare WLED UWVA	Active Area	309.37 X 174.02 (mm)
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight	309.37 X 174.02 (mm) 285 max.
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size	309.37 X 174.02 (mm) 285 max. 14.0 (inch)
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG)
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical)
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical) 60Hz
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical) 60Hz 250 nit typical
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical) 60Hz 250 nit typical 1920 x1080 (FHD)
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Backlight	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical) 60Hz 250 nit typical 1920 x1080 (FHD) LED
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Backlight Format of LCD Pixel Arrangement	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical) 60Hz 250 nit typical 1920 x1080 (FHD) LED RGB
Anti-Glare WLED UWVA 45 % cg 250 nits slim NB	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Backlight Format of LCD Pixel Arrangement Color Gamut Coverage	309.37 X 174.02 (mm) 285 max. 14.0 (inch) 3.0 (mm) max eDP1.2 Anti-glare (AG) None 700:1 (typical) 60Hz 250 nit typical 1920 x1080 (FHD) LED RGB 45% of NTSC

STORAGE AND DRIVES

Not all configuration components are available in all regions/countries. c06452802 — DA16554 - Worldwide — Version 3 — October 30, 2019

Technical Specifications

SSD 128 GB 2280 M2	Drive Weight	0.022 lb (10 g)	
SATA-3 TLC	Height	0.14 in (3.58 mm)	
	Width	0.87 in (22 mm)	
	Interface	ATA-8, SATA 3.0	
	Logical Blocks	250,069,680	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Security Features	ATA Security	
	Features	DIPM; TRIM; DEVSLP	
256 GB 2280 PCIe	Drive Weight	0.022 lb (10 g)	
NVMe Value	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X4	
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Security Features	ATA Security	
	Features	TRIM; L1.2	
256 GB 2280 PCle-3x2x2	Drive Weight	0.022 lb (10 g)	
NVMe+SSD 16 GB	Height	0.09 in (2.3 mm)	
3D Xpoint	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X4	
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Security Features	ATA Security	
	Features	TRIM; L1.2	

512 GB 2280 M2 PCIe-3x4	Drive Weight	0.022 lb (10 g)
SS NVMe TLC	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Security Features	ATA Security
	Features	TRIM; L1.2



Not all configuration components are available in all regions/countries. c06452802 — DA16554 - Worldwide — Version 3 — October 30, 2019

Technical Specifications

512 GB 2280 PCIe	Drive Weight	0.022 lb (10 g)
NVMe Value	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Security Features	ATA Security
	Features	TRIM; L1.2

NETWORKING/COMMUNICATIONS

Realtek RTL8822CE 802.11ac (2 x 2) Wi-Fi® and Bluetooth® 5 ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi [®] certified
	Frequency Band Data Rates	 802.11b/g/n 2.402 - 2.482 GHz 802.11a/n/ac 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points



Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 	
Power Consumption	 Transmit mode: 2.0 W Receive mode: 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW 	
Power Management	ACPI and PCI Express power saving mode	compliant power management 802.11 compliant
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OI LED White – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)



	Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps
		BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps
		1. Actual throughput may vary.
		Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
		Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
	Power Consumption	Peak (Tx) 330 mW
		Peak (Rx) 230 mW
		Selective Suspend 17 mW
	Bluetooth Software	Microsoft Windows Bluetooth Software
	Supported	
	Power Management	Microsoft Windows ACPI, and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	Power Management	ETS 300 328, ETS 300 826
	Certifications	Low Voltage Directive IEC950
		UL, CSA, and CE Mark
	Bluetooth Profiles	BT4.1-ESR 5/6/7 Compliance
	Supported	LE Link Layer Ping
	Supported	LE Dual Mode
		LE Link Layer
		LE Low Duty Cycle Directed Advertising
		LE L2CAP Connection Oriented Channels
		Train Nudging & Interlaced Scan
		BT4.2 ESR08 Compliance
		LE Secure Connection- Basic/Full
		LE Privacy 1.2 –Link Layer Privacy
		LE Privacy 1.2 – Extended Scanner Filter Policies
		LE Data Packet Length Extension
		FAX Profile (FAX)
		Basic Imaging Profile (BIP)2
		Headset Profile (HSP)
		Hands Free Profile (HFP)
		Advanced Audio Distribution Profile (A2DP)
		equired. Availability of public wireless access point is limited.
lard	nd ac of Sontombor 1 201/	products that utilize passive scanning on channel 12/13 and are capable of

1. Wireless access p 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® Wi-Fi 6¹ AX201 and Wireless LAN Standards IEEE 802.11a Bluetooth® 5 (802.11ax 2 x 2, non-vPro, supporting gigabit file

IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac **IEEE 802.11ax**



transfer speeds) non-vPro

Technical Specifications

	IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi [®] certified
Frequency Band	 802.11b/g/n/ax 2.402 – 2.482 GHz 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz) 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11ac VHT80(5GHz): +14.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 802.11ax HT40(2.4GHz): +10dBm minimum 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	 Transmit mode: 2.0 W Receive mode: 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW



Technical Specifications

Power Management	ACPI compliant power m	anagement	
-	802.11 compliant power	saving mode	
Receiver Sensitivity ⁴	 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS0: -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum 		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface		
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF LED Off – Radio ON		

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software



Technical Specifications

Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

POWER

65W EM	Dimensions (H x W x D)	102 x 55 x 30 mm	
	Weight	270 g +/- 10 g	
	Input	100 to 240 VAC	
		Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input



Technical Specifications

	Output current limit	<11.0 A Over voltage protection- 29 V max automatic shutdown	
Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords		
Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	
	Altitude	1 to 16,400 ft (0 to 5,000 m)	
	Humidity	20% to 95%	
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

45W	Dimensions	95 x 45 x 26.8 mm	
	Weight	200 g +/- 10 g	
	Input	100 to 240 VAC is missing	
		Input Efficiency	88.0 % at 115 VAC and 89.0 % at 230VAC
		Input frequency range	48 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0 A Over voltage protection- 29 V max automatic shutdown
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	1 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.



Technical Specifications

HP 3-cell Long Life Li-Ion (41 WHr)	Dimensions	6.0 x 186.85 x 90.2 mm (0.236 x 7.36 x 3.55 inch)
	Weight	0.195 kg (0.43 lb)
	Cells/Type	3 cell Lithium-Ion Prismatic cell / 496080/506080
	Voltage	11.55 V
	Amp-hour capacity	3.615 Ah/3.63 Ah
	Watt-hour capacity	41 Wh
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	Νο
	Warranty	1-year ²

1. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

2. Batteries have a default one year limited warranty.

FINGERPRINT SENSOR

Model	Elan eFSA80ST touch sensor
Mobile Voltage Operation	2.65V to 3.6V
Operating Temperature	-4° – 176°F (-20°- 80°C)
Current Consumption Image	50mA peak
Low Latency Wait for Finger	<900 uA
Capture Rate	20 cm/sec
ESD Resistance	IEC 61000-4-2 (+15KV)
Detection Matrix	508 DPI resolution / 4.0x4.0mm ² sensor area
FRR (False Reject Rate) / FAR (False Acceptance Rate)	FRR ~ 2% @ 1:50K FAR

Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Essential Messenger Case (up to 17.3")	H1D25AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HDMI to VGA Adapter	H4F02AA
	HP USB to Gigabit RJ45 Adapter	N7P47AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP Stereo USB Headset	T1A67AA
	HP Stereo 3.5mm Headset	T1A66AA
Power	HP 65W Smart AC Adapter	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 45W Smart Power Adapter	H6Y88AA
Storage	HP Mobile USB DVDRW	F2B56AA



Summary of Changes

Date of change:	Version History:		Description of change:
October 28, 2019	V1 to V2	Added	Environmental Section
October 30, 2019	V2 to V3	Updated	Processors Section

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